



## 30NM50

Power MOSFET

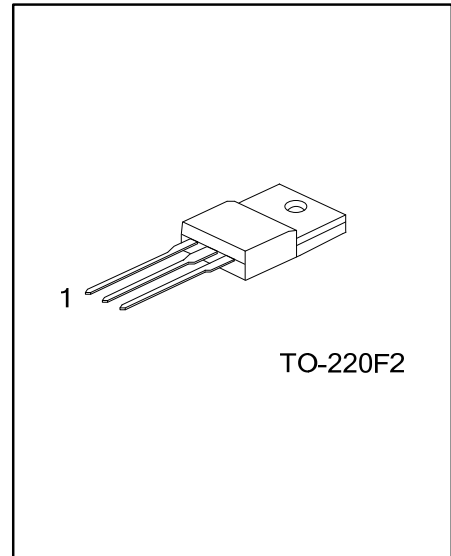
### 30A, 500V N-CHANNEL SUPER-JUNCTION MOSFET

#### DESCRIPTION

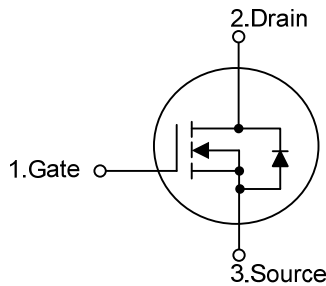
The **UTC 30NM50** is a Super Junction MOSFET Structure and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at AC-DC converters for power applications.

#### FEATURES

- \*  $R_{DS(ON)} \leq 90 \text{ m}\Omega @ V_{GS}=10V, I_D=15A$
- \* High Switching Speed
- \* 100% Avalanche Tested



#### SYMBOL



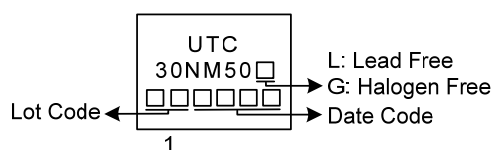
#### ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
30NM50L-TF2-T	30NM50G-TF2-T	TO-220F2	G	D	S	Tube

Note: Pin Assignment: G: Gate D: Drain S: Source

<p>30NM50G-TF2-T</p> <p>(1)Packing Type</p> <p>(2)Package Type</p> <p>(3)Green Package</p>	<p>(1) T: Tube</p> <p>(2) TF2: TO-220F2</p> <p>(3) G: Halogen Free and Lead Free, L: Lead Free</p>
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#### MARKING



■ ABSOLUTE MAXIMUM RATINGS (T<sub>c</sub>=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V <sub>DSS</sub>	500	V
Gate-Source Voltage		V <sub>GSS</sub>	±30	V
Drain Current	Continuous	I <sub>D</sub>	30	A
	Pulsed (Note 2)	I <sub>DM</sub>	60	A
Avalanche Energy	Single Pulsed (Note 3)	E <sub>AS</sub>	1242	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	8.2	V/nS
Power Dissipation		P <sub>D</sub>	42	W
Junction Temperature		T <sub>J</sub>	+150	°C
Storage Temperature		T <sub>STG</sub>	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. L = 60 mH, I<sub>AS</sub> = 6.4A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25Ω, Starting T<sub>J</sub> = 25°C

4. I<sub>SD</sub> ≤ 30A, di/dt ≤ 200A/μs, V<sub>DD</sub> ≤ BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C

■ THERMAL DATA

PARAMETER	SYMBOL	RATING	UNIT
Junction to Ambient	θ <sub>JA</sub>	62.5	°C/W
Junction to Case	θ <sub>JC</sub>	2.97	°C/W

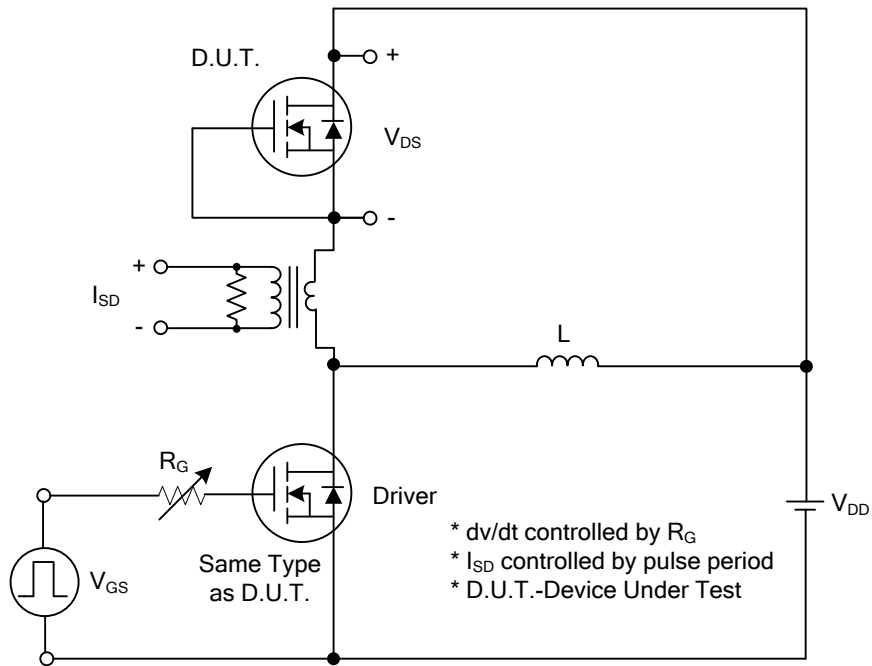
■ ELECTRICAL CHARACTERISTICS (T<sub>J</sub>=25°C, unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V	500			V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =500V, V <sub>GS</sub> =0V			10	μA
Gate- Source Leakage Current	I <sub>GSS</sub>	Forward			+100	nA
		Reverse			-100	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.5		4.5	V
Static Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =15A			90	mΩ
<b>DYNAMIC PARAMETERS</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, f=1.0MHz		2500		pF
Output Capacitance	C <sub>OSS</sub>			2225		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>			303		pF
<b>SWITCHING PARAMETERS</b>						
Total Gate Charge (Note 1)	Q <sub>G</sub>	V <sub>DS</sub> =400V, V <sub>GS</sub> =10V, I <sub>D</sub> =30A I <sub>G</sub> =1mA (Note1, 2)		106		nC
Gate to Source Charge	Q <sub>GS</sub>			21		nC
Gate to Drain Charge	Q <sub>GD</sub>			46		nC
Turn-ON Delay Time (Note 1)	t <sub>D(ON)</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =10V, I <sub>D</sub> =30A, R <sub>G</sub> =25Ω (Note1, 2)		30		ns
Rise Time	t <sub>R</sub>			67		ns
Turn-OFF Delay Time	t <sub>D(OFF)</sub>			340		ns
Fall-Time	t <sub>F</sub>			93		ns
<b>SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS</b>						
Maximum Body-Diode Continuous Current	I <sub>S</sub>				30	A
Maximum Body-Diode Pulsed Current	I <sub>SM</sub>				60	A
Drain-Source Diode Forward Voltage (Note 1)	V <sub>SD</sub>	I <sub>S</sub> =30A, V <sub>GS</sub> =0V			1.4	V
Body Diode Reverse Recovery Time (Note 1)	t <sub>rr</sub>	I <sub>S</sub> =30A, V <sub>GS</sub> =0V,		505		ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	di <sub>F</sub> /dt=100A/μs		9.7		μC

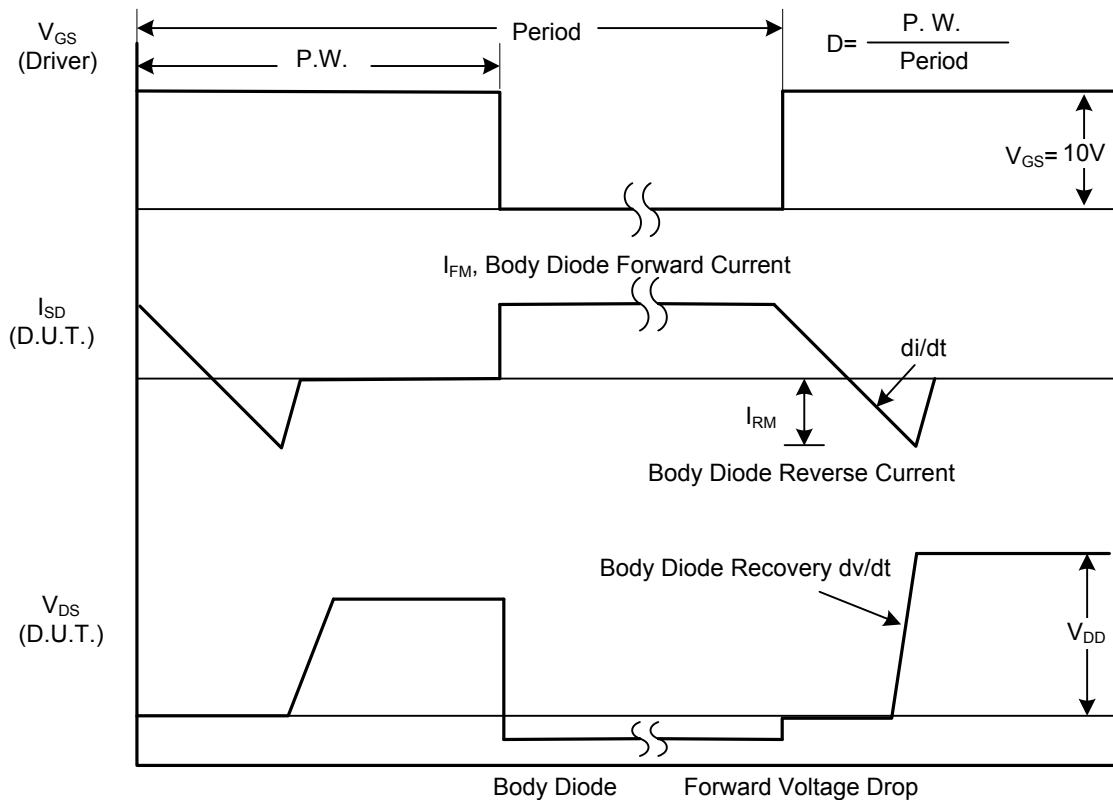
Notes: 1. Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2%.

2. Essentially independent of operating ambient temperature.

## TEST CIRCUITS AND WAVEFORMS



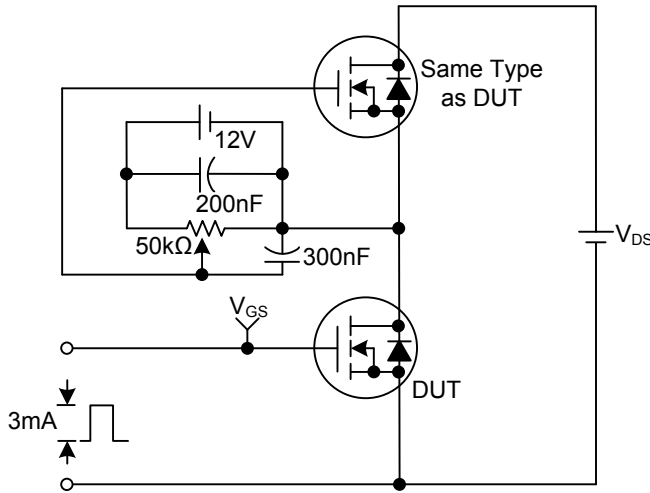
**Peak Diode Recovery dv/dt Test Circuit**



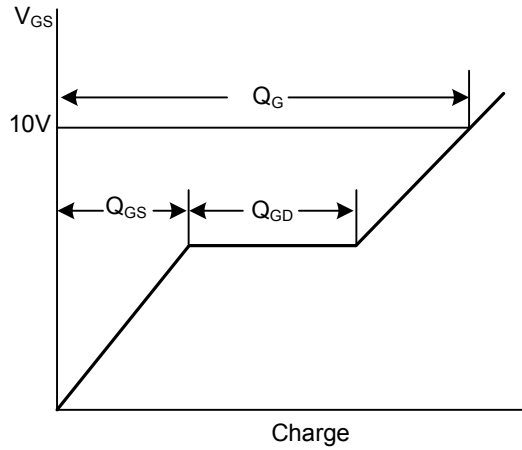
**Peak Diode Recovery dv/dt Waveforms**

## TEST CIRCUITS AND WAVEFORMS

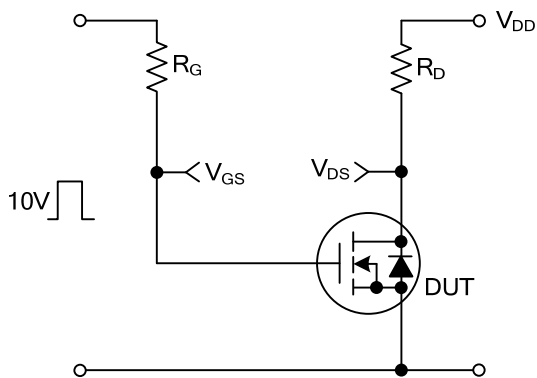
Gate Charge Test Circuit



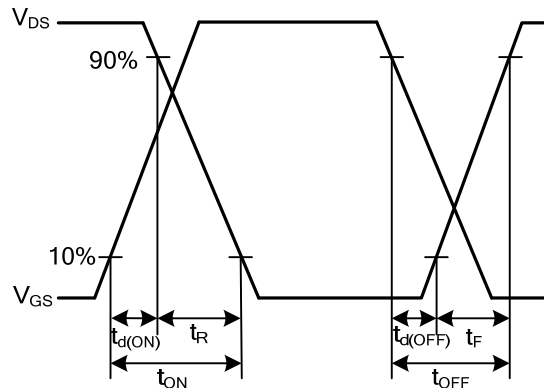
Gate Charge Waveforms



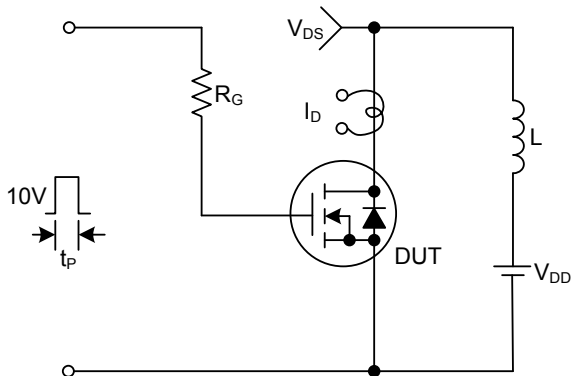
Resistive Switching Test Circuit



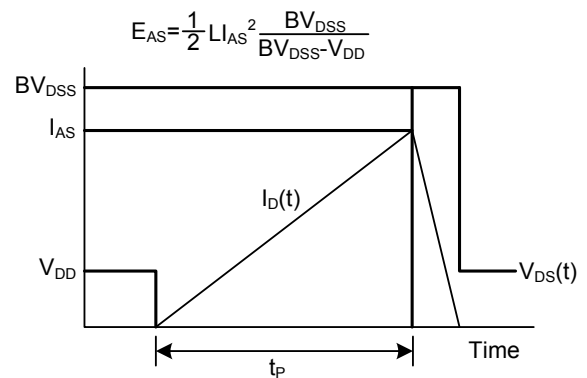
Resistive Switching Waveforms



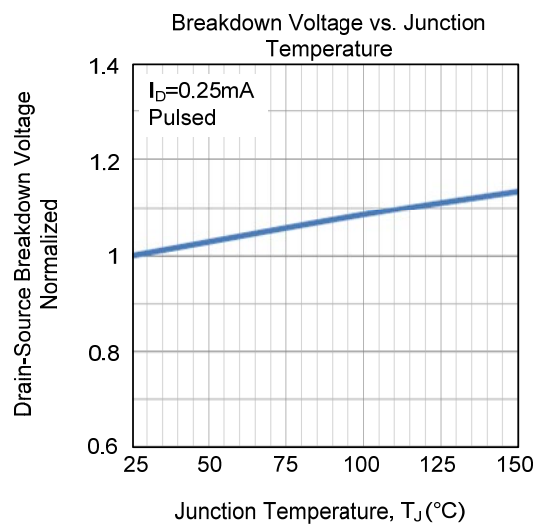
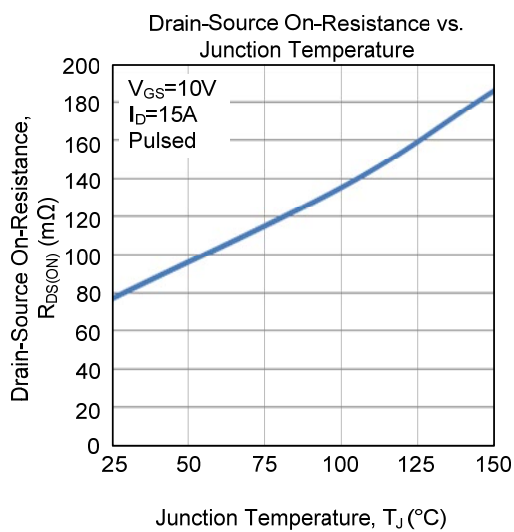
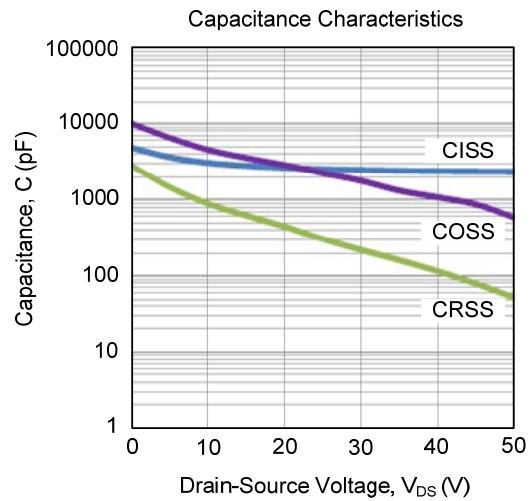
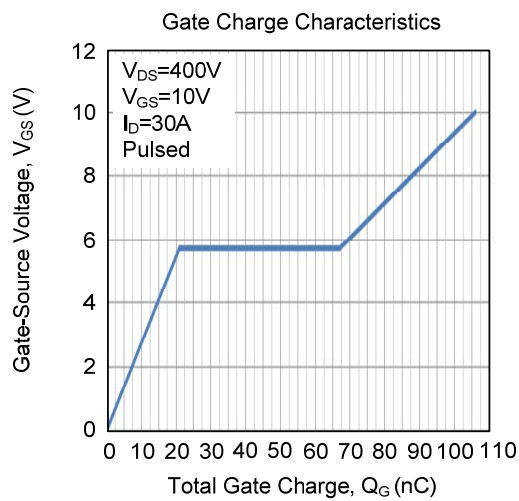
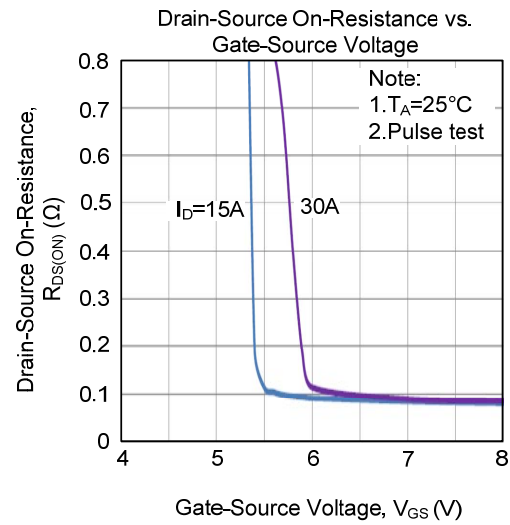
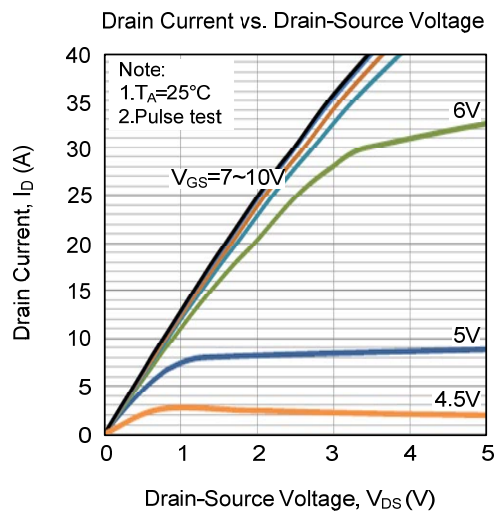
Unclamped Inductive Switching Test Circuit



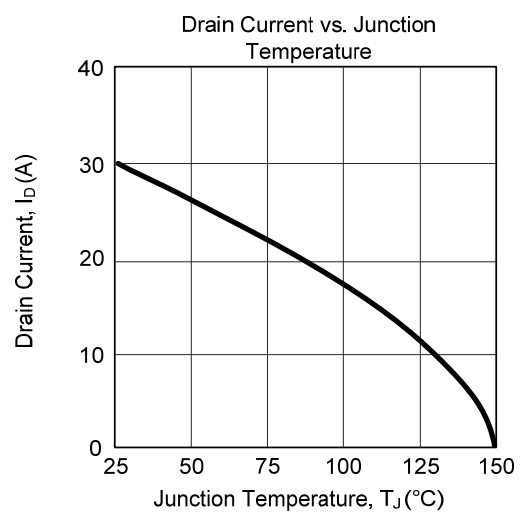
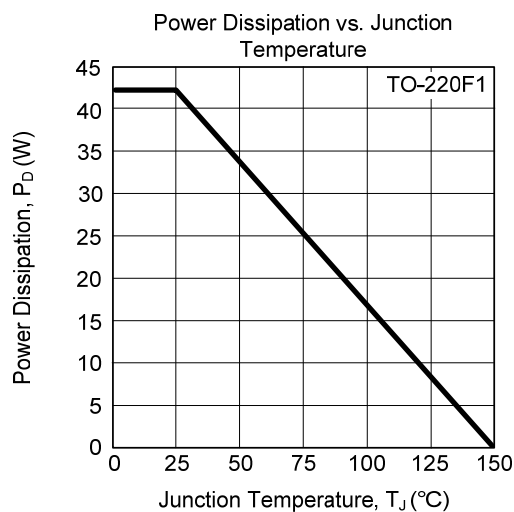
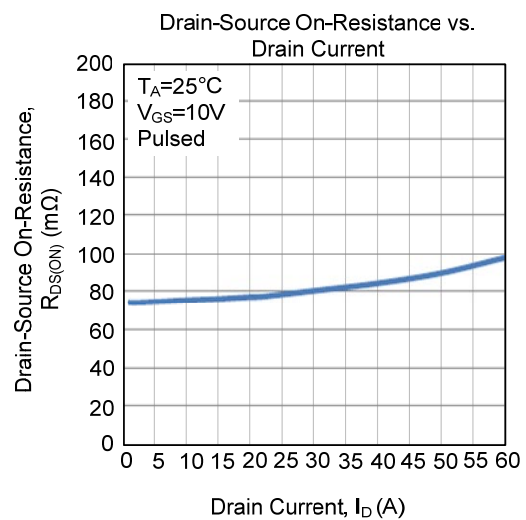
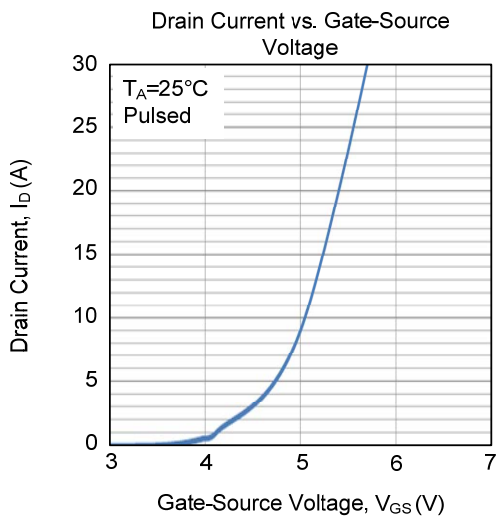
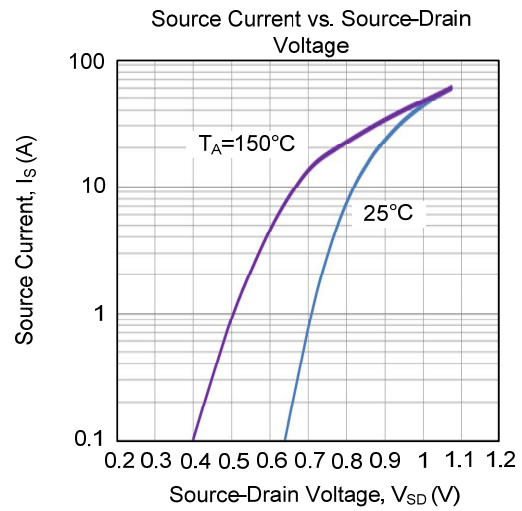
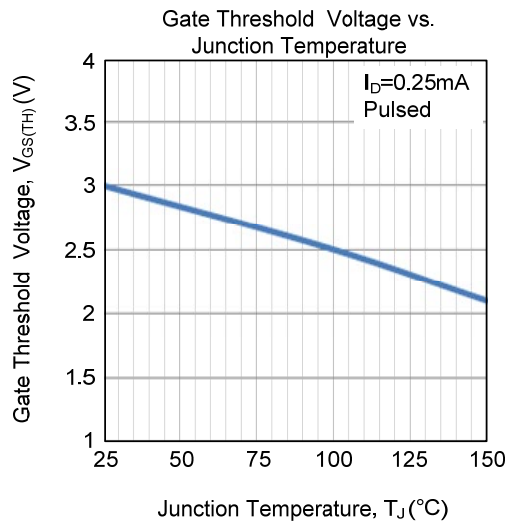
Unclamped Inductive Switching Waveforms



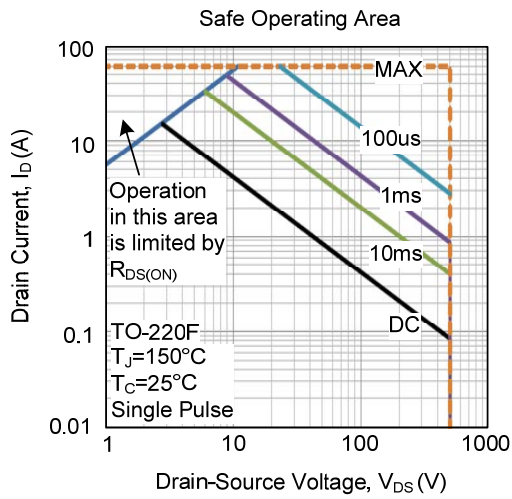
## TYPICAL CHARACTERISTICS



## ■ TYPICAL CHARACTERISTICS (Cont.)



■ TYPICAL CHARACTERISTICS (Cont.)



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